

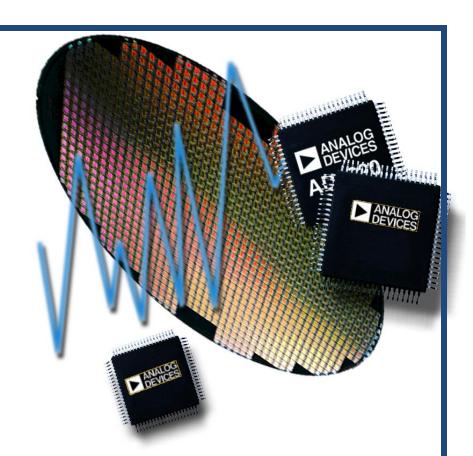


Analog Devices Welcomes Hittite Microwave Corporation

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Reliability Report

Report Title: Qualification Test Report

Report Type: See Attached

Date: See Attached

QTR: 2013-00256

Wafer Process: MESFET-D

Rev: 01

HMC121

HMC132

HMC132

HMC147

HMC168

HMC173

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- · Take the initiative to ensure product quality
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- · Continue to improve quality practices







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Introduction

The testing performed for this report is designed to accelerate the predominant failure mode, electro-migration (EM), for the devices under test. The devices are stressed at high temperature and DC biased to simulate a lifetime of use at typical operating temperatures. Using the Arrhenius equation, the acceleration factor (AF) is calculated for the stress testing based on the stress temperature and the typical use operating temperature.

This report is intended to summarize all of the High Temperature Operating Life Test (HTOL) data for the MESFET-D process. The FIT/MTTF data contained in this report includes all the stress testing performed on this process to date and will be updated periodically as additional data becomes available. Data sheets for the tested devices can be found at www.hittite.com.

Glossary of Terms & Definitions:

- 1. HTOL: High Temperature Operating Life. This test is used to determine the effects of bias conditions and temperature on semiconductor devices over time. It simulates the devices' operating condition in an accelerated way, through high temperature and/or bias voltage, and is primarily for device qualification and reliability monitoring. This test was performed in accordance with JEDEC JESD22-A108.
- 2. Operating Junction Temp (T_{oj}) : Temperature of the die active circuitry during typical operation.
- 3. Stress Junction Temp (T_{si}) : Temperature of the die active circuitry during stress testing.

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Qualification Sample Selection:

All qualification devices used were manufactured and tested on standard production processes and met pre-stress acceptance test requirements.

Summary of Qualification Tests:

HMC128 (QTR02003)

TEST	QTY IN	QTY OUT	PASS/FAIL	NOTES
Initial Electrical	33	33	Complete	
HTOL, 620 hours	33	33	Complete	
Post HTOL Electrical Test	33	33	Pass	
Bond Pull	5	5	Pass	
Die Shear	4	4	Pass	
SEM Inspection	5	5	Pass	
Metal and Dielectric Thickness	5	5	Pass	

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HMC129 (QTR02003)

TEST	QTY IN	QTY OUT	PASS/FAIL	NOTES
Initial Electrical	12	12	Complete	
HTOL, 1240 hours	12	12	Complete	
Post HTOL Electrical Test	12	12	Pass	
Bond Pull	5	5	Pass	
Die Shear	4	4	Pass	
SEM Inspection	5	5	Pass	
Metal and Dielectric Thickness	5	5	Pass	

HMC121 (QTR02006)

TEST	QTY IN	QTY OUT	PASS/FAIL	NOTES
Initial Electrical	35	35	Complete	
HTOL, 620 hours	35	35	Complete	
Post HTOL Electrical Test	35	35	Pass	
Bond Pull	10	10	Pass	
Die Shear	10	10	Pass	
SEM Inspection	5	5	Pass	
Metal and Dielectric Thickness	5	5	Pass	

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HMC182 (QTR02009)

TEST	QTY IN	QTY OUT	PASS/FAIL	NOTES
Initial Electrical	20	20	Complete	
HTOL, 1000 hours	20	20	Complete	
Post HTOL Electrical Test	20	20	Pass	

HMC182 (QTR02009)

TEST	QTY IN	QTY OUT	PASS/FAIL	NOTES
Initial Electrical	239	239	Complete	
HTOL, 720 hours	239	239	Complete	
Post HTOL Electrical Test	239	239	Pass	

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MESFET-D Failure Rate Estimate

Based on the HTOL test results, a failure rate estimation was determined using the following parameters:

With Device Operating Temp = 85° C

HMC128 (QTR02003)

Operating Junction Temp $(T_{oj}) = 85^{\circ}C(358^{\circ}K)$ Stress Junction Temp $(T_{si}) = 150^{\circ}C(423^{\circ}K)$

HMC129 (QTR02003)

Operating Junction Temp $(T_{oj}) = 85^{\circ}C(358^{\circ}K)$ Stress Junction Temp $(T_{sj}) = 150^{\circ}C(423^{\circ}K)$

HMC121 (QTR02006)

Operating Junction Temp $(T_{oj}) = 85^{\circ}C(358^{\circ}K)$ Stress Junction Temp $(T_{si}) = 150^{\circ}C(423^{\circ}K)$

HMC182 (QTR02009)

Operating Junction Temp $(T_{oj}) = 85^{\circ}C(358^{\circ}K)$ Stress Junction Temp $(T_{sj}) = 150^{\circ}C(423^{\circ}K)$

HMC182 (QTR02009)

Operating Junction Temp $(T_{oj}) = 85^{\circ}C(358^{\circ}K)$ Stress Junction Temp $(T_{sj}) = 150^{\circ}C(423^{\circ}K)$

Device hours:

HMC128 (QTR02003) = (33 X 620hrs) = 20,460 hours HMC129 (QTR02003) = (12 X 1240hrs) = 14,880 hours HMC121 (QTR02006) = (35 X 620hrs) = 21,700 hours HMC182 (QTR02009) = (20 X 1000hrs) = 20,000 hours HMC182 (QTR02009) = (239 X 720hrs) = 172,080 hours

For MESFET-D MMIC, Activation Energy = 1.6 eV

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$$AF = \exp\left[\left(\frac{E_A}{k}\right) \cdot \left(\left(\frac{1}{T_{USE}}\right) - \left(\frac{1}{T_{STRESS}}\right)\right)\right]$$

Acceleration Factor (AF):

HMC128 (QTR02003) Acceleration Factor = $\exp[1.6/8.6 \text{ e-5}(1/358-1/423)] = 2938.6$ HMC129 (QTR02003) Acceleration Factor = $\exp[1.6/8.6 \text{ e-5}(1/358-1/423)] = 2938.6$ HMC121 (QTR02006) Acceleration Factor = $\exp[1.6/8.6 \text{ e-5}(1/358-1/423)] = 2938.6$ HMC182 (QTR02009) Acceleration Factor = $\exp[1.6/8.6 \text{ e-5}(1/358-1/423)] = 2938.6$ HMC182 (QTR02009) Acceleration Factor = $\exp[1.6/8.6 \text{ e-5}(1/358-1/423)] = 2938.6$

Equivalent hours = Device hours x Acceleration Factor

Equivalent hours = (20,460x2938.6)+(14,880x2938.6)+(21,700x2938.6)+(20,000x2938.6)+(172,080x2938.6)=1.68x10⁸ hours

Since there were no failures and we used a time terminated test, F=0, and R=2F+2=2

The failure rate was calculated using Chi Square Statistic:

$$\lambda_{CL} = \frac{\chi^2_{\%CL,2f+2} \cdot 10^9}{2 \cdot t \cdot ss \cdot AF}$$
 at 60% and 90% Confidence Level (CL), with 0 units out of spec and a 85°C package backside temp;

Failure Rate

$$\lambda_{60} = [(\chi^2)_{60,2}]/(2X\ 1.68x10^8\)] = 1.8/\ 3.36x10^8 = 5.46x10^{-9}\ failures/hour\ or\ 5.5\ FIT\ or\ MTTF = 1.83x10^8\ Hours \\ \lambda_{90} = [(\chi^2)_{90,2}]/(2X\ 1.68x10^8\)] = 4.6/\ 3.36x10^8 = 1.38x10^{-8}\ failures/hour\ or\ 13.8FIT\ or\ MTTF = 7.27x10^7\ Hours$$

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